
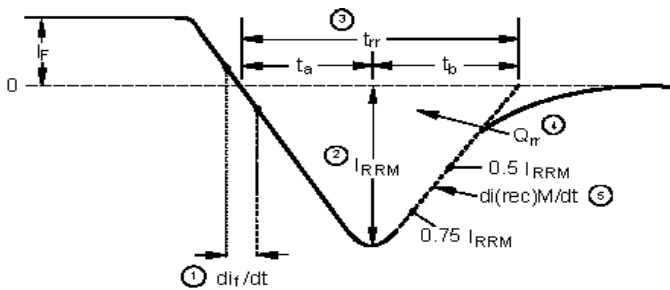
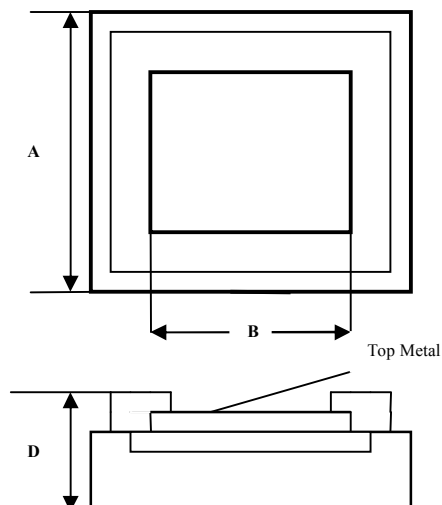
 VSP MIKRON 		8A/600V. Die Size-90*90mil.		
Electrical Characteristics	Symbol	Unit	Spec. limit	Die Sort
Breakdown Voltage @ $I_R=0,10\text{mA}$	V_B	V	600	620
Average Rectified Forward Current	$I_{F(AV)}$	A	8,0	-
DC Forward Voltage @ $25^\circ\text{C}, I_F=8,0\text{A}$	V_F	V	2,50	2,4
Maximum Reverse Current @ $25^\circ\text{C}, V_R=600\text{V}$ @ $125^\circ\text{C}, V_R=600\text{V}$	I_R	MA	0,010 0,500	0,009 0,450
Reverse Recovery Time, $I_F=1\text{A}, V_R=30\text{V}, di_F/dt=100\text{A}/\mu\text{S}.$	t_{rr}	nS	30	28
Operating Junction Temperature	T_J	$^\circ\text{C}$	175	



- di_f/dt - Rate of change of current through zero crossing
- I_{RRM} - Peak reverse recovery current
- t_{rr} - Reverse recovery time measured from zero crossing point of negative going I_F to point where a line passing through $0.75 I_{RRM}$ and $0.50 I_{RRM}$ extrapolated to zero current
- Q_{rr} - Area under curve defined by t_{rr} and I_{RRM}

$$Q_{rr} = \frac{t_{rr} \times I_{RRM}}{2}$$
- $di_{(rec)M}/dt$ - Peak rate of change of current during t_b portion of t_{rr}

DIM	ITEM	μm
A_x A_y	Die Size	2290 2290
B_x B_y	Top Metal Size	1640 1640
D	Thickness	350max.
Scribe line Width		60



Top metal: Al – for Wire Bonding.
Backside metal: Ti-Ni-Ag – for Soldering.
www.vsp-mikron.com